L Number	Hits	Search Text	DB	Time stamp
24	587	(chip or die) and ((substrate or board) with bismaleimide)	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 18:50
25	204	((chip or die) and ((substrate or board) with bismaleimide)) and (@ad<20000118)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 19:06
26	93	(((chip or die) and ((substrate or board) with bismaleimide)) and (@ad<20000118)) and (cure or curing)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 18:53
27	97	(((chip or die) and ((substrate or board) with bismaleimide)) and (@ad<20000118)) and ((b adj stage) or cure or curing)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 18:43
28	116	(((chip or die) and ((substrate or board) with bismaleimide)) and (@ad<20000118)) and ((b adj stage) or cure or curing or cured)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 18:43
29	12	(chip or die) and ((solder adj mask) with bismaleimide)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 18:45
30	4	((chip or die) and ((solder adj mask) with bismaleimide)) and (@ad<20000118)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 18:54
31	175	(chip or die) and ((solder adj mask) with adhesive)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 19:05
32	47	((chip or die) and ((solder adj mask) with adhesive)) and (adhesive with (cure or curing or (b adj stage)))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 19:17
33	17	(((chip or die) and ((solder adj mask) with adhesive)) and (adhesive with (cure or curing or (b adj stage)))) and (@ad<20000118)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 19:23
35	2678	(chip or die) with ((polyimide or mask) and adhesive)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 19:06
36	930	(chip or die) with (mask and adhesive)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 19:35
37	371	((chip or die) with (mask and adhesive)) and (@ad<20000118)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2004/06/07 19:07
38	11	(((chip or die) with (mask and adhesive)) and (@ad<20000118)) and (((partial near (cure or curing)) or (b adj stage)))	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/06/07 19:36

30		1 / (a b d a a a d d a b a a d b a a d a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a d a a b a a d a a b a a d a a b a a d a a b a a d a a b a a d a a d a a b a a d a a d a a b a a d a a b a a d a a b a a d a a b a a d a a a a a a a a a a a a a a a a a a a a	IICDAM.	2004/06/07
39	92	((chip or die) with (mask and adhesive))	USPAT;	2004/06/07 19:23
		and ((chip or die) and ((solder adj mask)	US-PGPUB;	19:23
•		with adhesive))	EPO; JPO;	
			DERWENT;	
10		///	IBM_TDB	2004/06/07
40	22	, , , , , , , , , , , , , , , , , , , ,	USPAT;	2004/06/07
		and ((chip or die) and ((solder adj mask)	US-PGPUB;	19:36
		with adhesive))) and (@ad<20000118)	EPO; JPO; DERWENT;	
			IBM TDB	
41	54	5336931.URPN.	USPAT	2004/06/07
41	24	3336931.0RFN.	USPAI	19:34
42	11197	(chip or die) and mask and adhesive	USPAT;	2004/06/07
74	1119/	(Chip of die) and mask and adnesive	US-PGPUB;	19:35
			EPO; JPO;	10.00
			DERWENT;	
	ŀ		IBM TDB	
43	502	((chip or die) and mask and adhesive) and	USPAT;	2004/06/07
13	302	(((partial near (cure or curing)) or (b	US-PGPUB;	19:36
		adj stage)))	EPO; JPO;	20,00
			DERWENT;	
			IBM TDB	
44	265	(((chip or die) and mask and adhesive)	USPAT;	2004/06/07
		and (((partial near (cure or curing)) or	US-PGPUB;	19:37
		(b adj stage)))) and (@ad<20000118)	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
45	181	((((chip or die) and mask and adhesive)	USPAT;	2004/06/07
		and (((partial near (cure or curing)) or	US-PGPUB;	19:54
		(b adj stage)))) and (@ad<20000118)) and	EPO; JPO;	
		(outgass or outgassing or gas or voids)	DERWENT;	
			IBM_TDB	
46	84	, , , , , , , , , , , , , , , , , , ,	USPAT;	2004/06/07
		and (((partial near (cure or curing)) or	US-PGPUB;	19:54
		(b adj stage)))) and (@ad<20000118)) not	EPO; JPO;	
		((((chip or die) and mask and adhesive)	DERWENT;	
		and (((partial near (cure or curing)) or	IBM_TDB	
		(b adj stage)))) and (@ad<20000118)) and		.
		(outgass or outgassing or gas or voids))		